

Bluetooth® SMD Module

Module Solder Reflow Conditions

1) Leaded Solder Reflow Condition

Reflow Temperature: 493.15K (220 degree), Time 20 to 30 sec,
Peak 503.15K (230 degree) Max

Preheat Temperature: 433.15K +/- 10K (160 degree +/- 10 degree),
Time 90 sec +/- 30 sec

2) Lead-free Solder Reflow Condition

Reflow Temperature: 503.15K (230 degree), Time 30 to 40 sec,
Peak 523.15K (250 degree) Max

Preheat Temperature: 438.15K +/- 15K (165 degree +/- 15 degree),
Time 90 to 120 sec

Reflow Time: One time

ESD Susceptibility

This module meets the below ESD test specifications.

1) Human Body Model (HBM)

+/-2.0k Volts as C=100pF and R=1.5kohms
Number of test: Three times
Measurement shall be conducted after that.

2) Machine Model (MM)

+/-200 Volts as C=200pF / R=0 ohm
Number of test: One time
Measurement shall be conducted after that.